



SOFT, FREESTANDING GAP FILLER

Tflex[™] 200 V0 is a very soft, freestanding gap filler that is more compliant than most other gap fillers. Combining good thermal conductivity of 1.1 W/mK with high conformability, this gap filler produces low thermal resistance. The alumina filler allows the product to remain a cost effective solution where moderate thermal performance is acceptable.

Tflex 200V0's silicone and ceramic technology allows a combination of great reliability, good thermal performance, and easy handling.

FEATURES

- Soft and compliant for low stress applications
- Naturally tacky needing no further adhesive coating
- 1.1 W/mK thermal conductivity
- Available in thicknesses from 0.020" (0.51mm) to 0.200" (5.0mm)

APPLICATIONS

- Cooling components to the chassis or frame
- High speed mass storage drives
- RDRAM memory modules
- Heat pipe thermal solutions
- Automotive engine control units
- Wireless communication hardware

Tflex™ 200 V0 Series

Thermal Gap Filler

	TFLEX™ 200 V0	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	
Color	Light Gray	Visual
Thickness Range	0.020" (0.51mm) - 0.200" (5.08mm)	
Thickness Tolerance	± 10%	
Density (g/cc)	1.73	Helium Pycnometer
Hardness	60 Shore 00	ASTM D2240
Outgassing Conditions	Post Cured	
Outgassing TML (weight %)	0.34%	ASTM E595
Outgassing CVCm (weight %)	0.10%	ASTM E595
UL Flammability Rating	94 V0	UL FILE E1808040
Temperature Range	-45°C to 160°C	
Thermal Conductivity	1.1 W/mK	Hot Disk
Thermal Resistance @ 40 mils, 10 psi @ amm, 69kPa	1.57°C-in ² /W 10.13°C-cm ² /W	ASTM D5470 (modified)
Coefficient of Thermal Expansion	229 ppm/°C 35°C to 130°C	IPC-TM-650 2.4.24
Volume Resistivity	4 x 10 ¹³ ohm-cm	ASTM D257
Dielectric Constant @ 1MHz	5.5	

STANDARD THICKNESSES

0.020 to 0.200-inch (0.5 to 5.0mm)

0.020 to 0.200-inch thick material available in 0.010-inch (0.25mm) increments

Inquire about availability of material and options above 0.200-inches

STANDARD SHEET SIZES

18" x 18" (457mm x 457mm) and 9" x 9" (229mm x 229mm) Tflex™ 200V0 may be die cut into individual shapes. Pressure sensitive adhesive is not applicable for Tflex™ 200V0 products.

REINFORCEMENT

0.020" (0.51mm) and 0.030" (0.762mm) are fiberglass reinforced.

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

THR-DS-TFLEX-200V0_0714

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